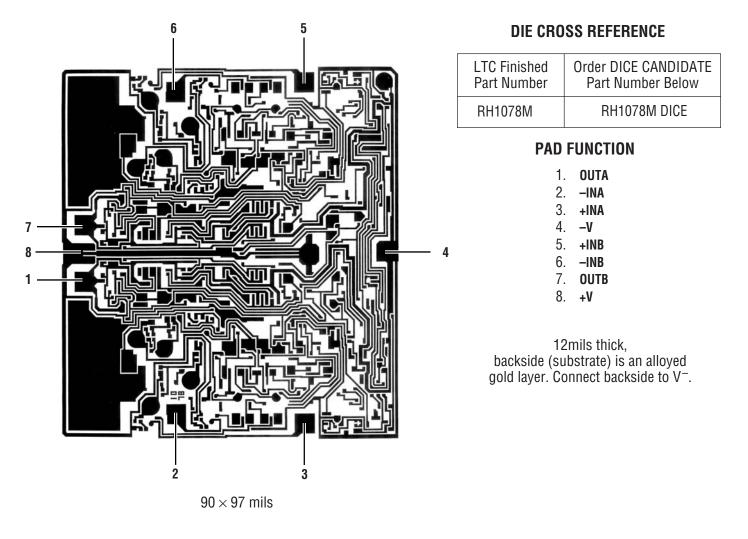


DICE SPECIFICATION

RH1078M Micropower, Dual, Single Supply Precision Op Amp



DICE ELECTRICAL TEST LIMITS $V_S = 5V$, $V_{CM} = 0.1V$, $V_{OUT} = 1.4V$ unless otherwise specified.

				T _A = 25°C	
SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNITS
V _{OS}	Input Offset Voltage			120	μV
l _{os}	Input Offset Current			0.8	nA
I _B	Input Bias Current			15	nA



RH1078M

DICE ELECTRICAL TEST LIMITS $V_S = 5V$, $V_{CM} = 0.1V$, $V_{OUT} = 1.4V$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	T _A = 25°C		
			MIN	MAX	UNITS
CMRR	Common Mode Rejection Ratio	V _{CM} = 0V to 3.5V V _{CM} = 0.05V to 3.2V	94		dB dB
PSRR	Power Supply Rejection Ratio	$V_{S} = 2.3V \text{ to } 12V$ $V_{S} = 3.1V \text{ to } 12V$	100		dB dB
A _{VOL}	Large-Signal Voltage Gain	$ \begin{array}{l} V_0 = 0.03 V \ to \ 4V, \ No \ Load \\ V_0 = 0.03 V \ to \ 3.5V, \ R_L = 50 k \\ V_0 = 0.05 V \ to \ 4V, \ No \ Load \\ V_0 = 0.05 V \ to \ 3.5V, \ R_L = 50 k \end{array} $	150 120		V/mV V/mV V/mV V/mV
Vout	Output Voltage Swing	Output Low, No Load Output Low, 2k to GND Output Low, I _{SINK} = 100µA Output High, No Load Output High, 2k to GND	4.2 3.5	6 2 130	mV mV mV V V
SR	Slew Rate	$A_V = 1, V_S = \pm 2.5V$	0.04		V/µs
I _S	Supply Current	Per Amplifier		75	μA
	Minimum Supply Voltage	Note 1		2.3	V
V _{OS}	Input Offset Voltage			350	μV
l _{0S}	Input Offset Current			0.8	nA
I _B	Input Bias Current			15	nA
	Input Voltage Range		13.5 15.0		V V
CMRR	Common Mode Rejection Ratio	V _{CM} = 13.5V, -15V V _{CM} = 13V, -14.9V	97		dB dB
PSRR	Power Supply Rejection Ratio	$V_{\rm S}$ = 5V, 0V to ±18V	100		dB
A _{VOL}	Large-Signal Voltage Gain	$ \begin{array}{l} V_{0}=\pm 10V,R_{L}=50k\\ V_{0}=\pm 10V,R_{L}=2k\\ V_{0}=\pm 10V,R_{L}=5k \end{array} $	1000 300		V/mV V/mV V/mV
V _{OUT}	Output Voltage Swing	$ \begin{array}{l} R_L = 50k \\ R_L = 2k \\ R_L = 5k \end{array} $	±13 ±11		V V V
SR	Slew Rate		0.06		V/µs
I _S	Supply Current	Per Amplifier		100	μA

Note 1: Power supply rejection ratio is measured at the minimum supply voltage.

Wafer level testing is performed per the indicated specifications for dice. Considerable differences in performance can often be observed for dice versus packaged units due to the influences of packaging and assembly on certain devices and/or parameters. Please consult factory for more information on dice performance and lot qualifications via lot sampling test procedures.

Dice data sheet subject to change. Please consult factory for current revision in production.

I.D.No. 66-13-1078



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